

AMENDMENT

Serial Number: 09/652619

Filing Date: August 31, 2000

Title: METHOD FOR FORMING A METALLIZATION LAYER

Page 17

Dkt: 303.085US4

REMARKS

No claims are amended, no claims are canceled, and claims 152-187 (formerly claims 55-90) are reinstated; as a result, claims 21-25, 27, 29, 91, and 99-187 are now pending in this application.

Applicant submits this Amendment to reinstate claims formerly submitted 55-90 as new claims 152-187 for consideration with the previously-allowed claims. A portion of the claim set history is provided for the convenience of the examiner.

- In a Supplemental Preliminary Amendment dated November 16, 2000, Applicant canceled claims 1-20 and added claims 21-54.
- In an Office Action dated May 21, 2001, the claims were restricted to one of the following:
 - I. Claims 21-31 drawn to an integrated circuit (class 257, subclass 500+).
 - II. Claims 32-38 drawn to semiconductor manufacturing system (class 118, subclass 500+).
 - III. Claims 39-54 drawn to method of forming an integrated circuit (class 438, subclass 629).
- In a Response dated June 22, 2001, Applicant elected group I (claims 21-31) and added new claims 55-99.
- In an Office Action dated September 25, 2001, the claims were restricted to one of the following:
 - I. Claims 21-31 and 91-99 drawn to an integrated circuit (class 257, subclass 500+).
 - II. Claims 55-72 drawn to an integrated circuit with a copper metallization layer (class 257, subclass 500+).
 - III. Claims 73-81 drawn to an integrated circuit with a nickel metallization layer (class 257, subclass 629).
 - IV. Claims 82-90 drawn to an integrated circuit with a palladium metallization layer (class 257, subclass 700+).

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Page 18

Dkt: 303.085US4

In this Office Action, claims 21-31 and 55-99 were found to be generic to a plurality of disclosed patentably distinct species comprising various types of metallization layers for forming the second layer of the integrated circuit. Some of claims 21-31 and 55-99 were subsequently amended.

- In a Response dated October 25, 2001, Applicant elected Group I (claims 21-31) and canceled groups II-IV (claims 55-90).
- In a Response dated July 18, 2002, Applicant added new claims 100-151.
- In a Notice of Allowability dated December 3, 2002, claims 21-25, 27, 29, 91 and 99-151 were identified as being allowed.

Although not expressly identified as such, the Office Action dated September 25, 2001 is, in substance, a restriction to one of four identified species. In accordance with 37 CFR §1.141, Applicant respectfully requests reconsideration of the claims drawn to the non-elected species (claims 55-90). As these claims were previously canceled, Applicant reinstates previously canceled claims 55-90 as newly numbered claims 152-187 in accordance with 37 CFR 1.121(c)(2).

Should the Examiner determine that the reinstated claims do not include all the limitations of an allowed generic claim in accordance with 37 CFR §1.141, Applicant respectfully requests the Examiner to call the Applicant's representative at 612-373-6960 to discuss including such limitations to place these reinstated claims in condition for allowance.

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Page 19

Dkt: 303.085US4

CONCLUSION

The Examiner is invited to telephone Applicant's attorney at (612) 373-6960 to facilitate prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743

Respectfully submitted,

GURTEJ S. SANDHU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 373-6960

Date 12-9-03

By

Mr. L.B.
Marvin L. Beckman
Reg. No. 38,377

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below.

Z:lt
Tina M. Kohout12/9/03
Date of Transmission